Series 655000 TSOP-to-DIP 0.600 [15.24]
Adapter

FEATURES
• Designed to allow user to cut 32-position adapter down to any size desired.
• Pins are mechanically fastened and soldered to board using Aries' patented process, creating a reliable electrical connection and rugged contact.

GENERAL SPECIFICATIONS
• ADAPTER BODY: FR-4 with 1-oz. Cu traces
• PADS: bare Cu protected with Entek® by Enthone or immersion white Sn to eliminate coplanarity concerns and solder bridges associated with hot air solder leveling
• PINS: Brass 360 1/2-hard per UNS C36000, ASTM B16/B16M
• PIN PLATING: 200µ [5.08µ] Sn/Pb 93/7 per ASTM B579-73 over 100µ [2.54µ] Ni per SAE AMS-QQ-N-290
• OPERATING TEMPERATURE: 221°F [105°C]

MOUNTING CONSIDERATIONS
• SUGGESTED PCB HOLE SIZE: 0.028 ±0.003 [0.71 ±0.08] dia.
• Will plug into standard IC sockets

CUSTOMIZATION: In addition to the standard products shown on this page, Aries specializes in custom design and production. Special materials, platings, sizes, and configurations can be furnished, depending on the quantity. NOTE: Aries reserves the right to change product general specifications without notice.

ORDERING INFORMATION
32-655000-10
32-655000-10-P for Panelized Version

ALL DIMENSIONS: INCHES [MILLIMETERS]
ALL TOLERANCES: ±0.005 [0.13] UNLESS OTHERWISE SPECIFIED
CONSULT FACTORY FOR OTHER SIZES AND CONFIGURATIONS